



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

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# PRINTED CIRCUIT BOARDS

01

24.04.2015

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04	163	FR4	35	L41.35	P18	S1
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columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_163\_FR4\_35\_L41.35\_p18\_s1

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		B
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-2	35 $\mu$	Copper	A1	B
	410 $\mu$	L-FR4		
Layer-3	35 $\mu$	Copper	A1	B
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-99	35 $\mu$	Copper	A1	B

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